

# APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate                             |
|------------------------|---|
| то:                    | Please return this copy as a certification of your approval |
| Part No.:              | Checked & Approved by:                                      |
| Customer's Part No.:   | Date:   |

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| Part No. | : | SFR315K   |
|----------|---|-----------|
| Pages    | : | 6         |
| Date     | : | 2015/1/21 |
| Revision | • | 1.0       |



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|--------------|-----|
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#### **Features**

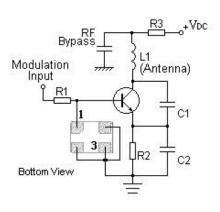
- 1-port Resonator
- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 3.20x2.50x0.70mm³
- Electrostatic Sensitive Device(ESD)

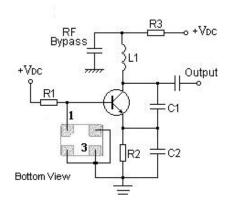


## **Application**

Typical Low-Power Transmitter Application

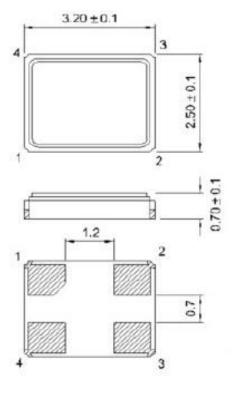
Typical Local Oscillator Application





#### **Package Dimensions (DCC4C)**

**Pin Configuration** 



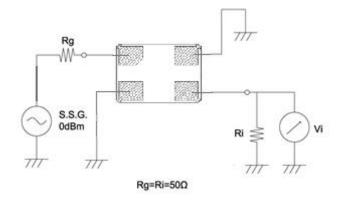
| 1   | Input/ Output |  |
|-----|---------------|--|
| 3   | Output/ Input |  |
| 2,4 | Ground        |  |

#### Marking

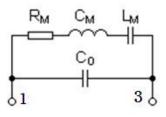


| SF   | Trademark     |  |  |
|------|---------------|--|--|
| R    | SAW Resonator |  |  |
| 315K | Part number   |  |  |

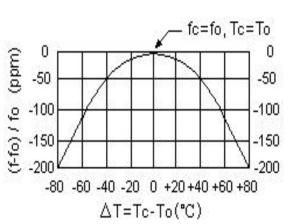
#### **Test Circuit**



# **Equivalent LC Model**

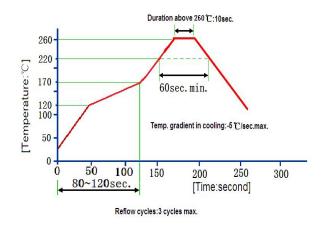


#### **Temperature Characteristics**



The curve shown above accounts for resonator Please read notes at the end of this document.

# **Recommended Reflow Soldering Diagram**



**Performance** 

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2015/1/21

#### **Maximum Rating**

| ltem                  |                  | Value      | Unit          |
|-----------------------|------------------|------------|---------------|
| DC Voltage            | $V_{DC}$         | 10         | V             |
| Operation Temperature | Т                | -40 ~ +85  | ${\mathbb C}$ |
| Storage Temperature   | T <sub>stg</sub> | -55 ~ +125 | $^{\circ}$    |
| RF Power Dissipation  | Р                | 10         | dBm           |

#### **Electronic Characteristics**

Test Temperature: 25°C±2°C

Terminating source impedance:  $50\Omega$  Terminating load impedance:  $50\Omega$ 

|  | Item                              |                | Minimum | Typical     | Maximum | Unit       |
|--|-----------------------------------|----------------|---------|-------------|---------|------------|
| Center   | Absolute Frequency                | fc             |         | 315.00      |         | MHz        |
| Frequency  | Tolerance from 315.00MHz          | △fc            |         | ± <b>75</b> |         | KHz        |
| Insertion Loss(n                                     | nin)                              | IL             |         | 1.3         | 2.0     | dB         |
| Quality Factor                                       | Unloaded Q                        | Qu             |         | 21571       |         |            |
| Quality Factor                                       | 50Ω Loaded Q                      | QL             |         | 3559        |         |            |
| Temperature<br>Stability                             | Turnover Temperature              | T <sub>0</sub> | 25      | 40          | 55      | $^{\circ}$ |
|  | Frequency Temperature Coefficient | FTC            |         | 0.032       |         | ppm/℃      |
| Frequency Aging Absolute Value during the First Year |                                   | f <sub>A</sub> |         | ≤10         |         | ppm/yr     |
| DC Insulation Resistance between Any Two Pins        |                                   |                | 1.0     |             |         | МΩ         |
| RF<br>Equivalent<br>RLC<br>Model                     | Motional Resistance               | R <sub>M</sub> |         | 19.7        | 22.0    | Ω          |
|  | Motional Inductance               | L <sub>M</sub> |         | 215.5       |         | μН         |
|  | Motional Capacitance              | См             |         | 1.18        |         | fF         |
|  | Static Capacitance                | C <sub>0</sub> | 1.80    | 2.08        | 2.4     | pF         |

#### **Frequency Response**



## Reliability (The SAW components shall remain electrical performance after tests)

| No | Test item                          | Test condition  |  |  |
|----|------------------------------------|---|--|--|
| 1  | Temperature<br>Storage             | (1) Temperature: 85℃±2℃, Duration: 250h,Recovery time: 2h±0.5h<br>(2) Temperature: –55℃±3℃, Duration: 250h,Recovery time: 2h±0.5h                         |  |  |
| 2  | Humidity Test                      | Conditions: 60℃±2℃,90~95% RH  |  |  |
| 3  | Thermal<br>Shock                   | Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min , Cycle time: 100 times , Recovery time : 2h±0.5h.                      |  |  |
| 4  | Vibration<br>Fatigue               | Frequency of vibration: 10~55Hz Amplitude:1.5mm  Directions: X,Y and Z Duration: 2h   |  |  |
| 5  | Drop Test                          | Cycle time: 10 times Height: 1.0m   |  |  |
| 6  | Solder Ability<br>Test             | Temperature: 245℃±5℃ Duration: 3.0s5.0s  Depth: DIP2/3 , SMD1/5   |  |  |
| 7  | Resistance to<br>Soldering<br>Heat | (1)Thickness of PCB:1mm,Solder condition: 260°C±5°C,Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time: 2 ± 0.5h |  |  |

#### **Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by

electrostatic, so we should pay attention to **ESD protect** in the test.

2. **Static voltage** between signal load and ground may cause deterioration and destruction of the

component. Please avoid static voltage.

3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic

cleaning.

- 4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.